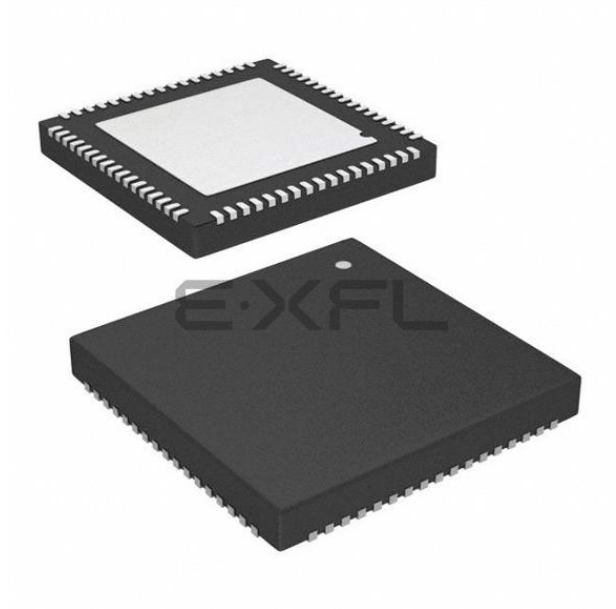
Infineon Technologies - CY8C3865LTI-045 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	67MHz
Connectivity	EBI/EMI, I²C, LINbus, SPI, UART/USART
Peripherals	CapSense, DMA, POR, PWM, WDT
Number of I/O	38
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x20b; D/A 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-VFQFN Exposed Pad
Supplier Device Package	68-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c3865lti-045

Figure 2-4. 100-pin TQFP Part Pinout

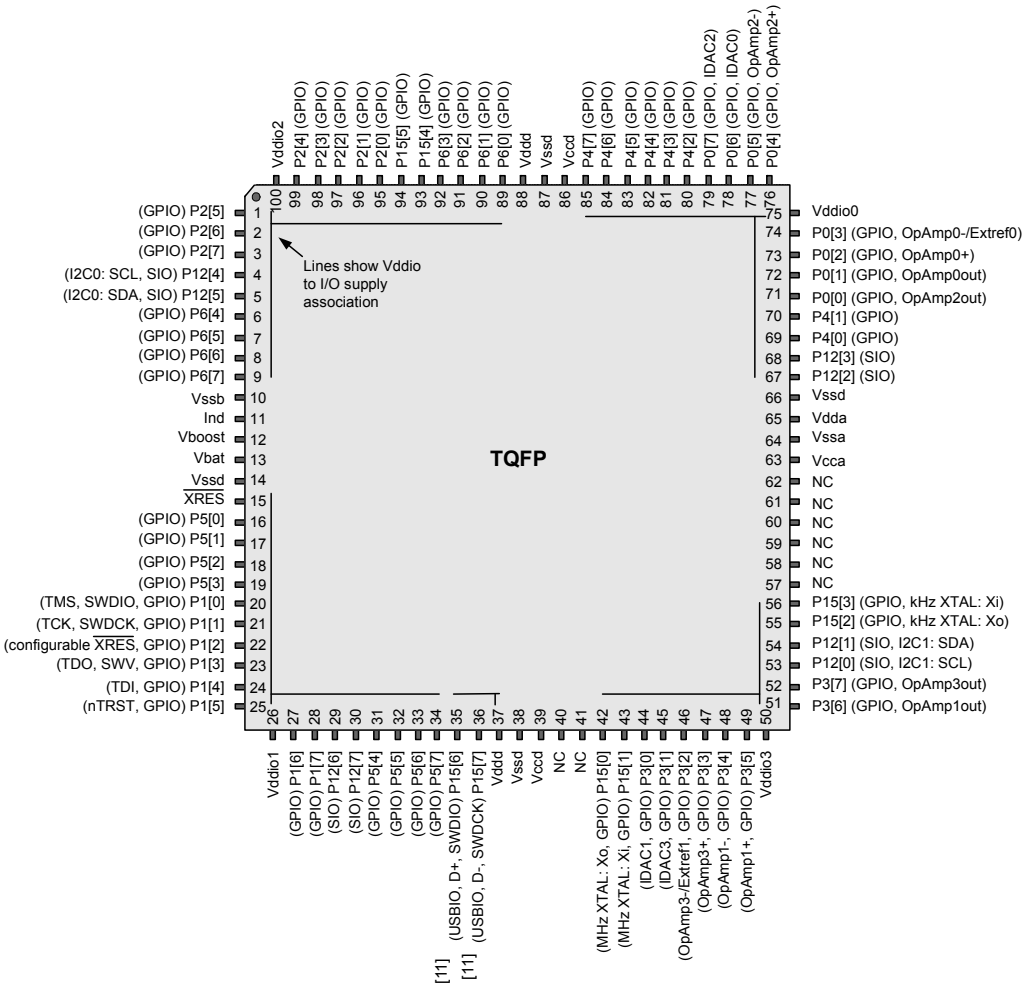


Figure 2-5 and Figure 2-6 show an example schematic and an example PCB layout, for the 100-pin TQFP part, for optimal analog performance on a two-layer board.

- The two pins labeled Vddd must be connected together.
- The two pins labeled Vccd must be connected together, with capacitance added, as shown in Figure 2-5 and Power System on page 24. The trace between the two Vccd pins should be as short as possible.
- The two pins labeled Vssd must be connected together.

Note
11. Pins are Do Not Use (DNU) on devices without USB. The pin must be left floating.

6.2.1 Power Modes

PSoC 3 devices have four different power modes, as shown in Table 6-2 and Table 6-3. The power modes allow a design to easily provide required functionality and processing power while simultaneously minimizing power consumption and maximizing battery life in low-power and portable devices.

PSoC 3 power modes, in order of decreasing power consumption are:

- Active
- Alternate Active
- Sleep
- Hibernate

Active is the main processing mode. Its functionality is configurable. Each power controllable subsystem is enabled or disabled by using separate power configuration template registers. In alternate active mode, fewer subsystems are enabled, reducing power. In sleep mode most resources are disabled regardless of the template settings. Sleep mode is optimized to provide timed sleep intervals and Real Time Clock functionality. The lowest power mode is hibernate, which retains register and SRAM state, but no clocks, and allows wakeup only from I/O pins. Figure 6-5 on page 26 illustrates the allowable transitions between power modes

Table 6-2. Power Modes

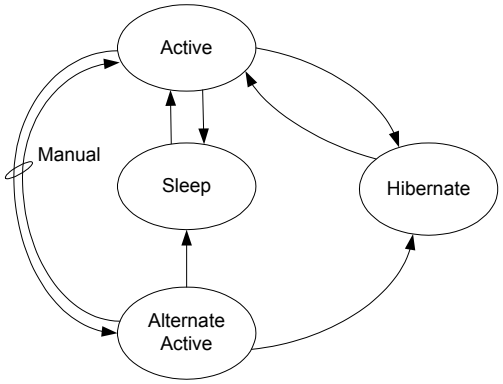
Power Modes	Description	Entry Condition	Wakeup Source	Active Clocks	Regulator
Active	Primary mode of operation, all peripherals available (programmable)	Wakeup, reset, manual register entry	Any interrupt	Any (programmable)	All regulators available. Digital and analog regulators can be disabled if external regulation used.
Alternate Active	Similar to Active mode, and is typically configured to have fewer peripherals active to reduce power. One possible configuration is to use the UDBs for processing, with the CPU turned off	Manual register entry	Any interrupt	Any (programmable)	All regulators available. Digital and analog regulators can be disabled if external regulation used.
Sleep	All subsystems automatically disabled	Manual register entry	Comparator, PICU, I^2C, RTC, CTW, LVD	ILO/kHzECO	Both digital and analog regulators buzzed. Digital and analog regulators can be disabled if external regulation used.
Hibernate	All subsystems automatically disabled Lowest power consuming mode with all peripherals and internal regulators disabled, except hibernate regulator is enabled Configuration and memory contents retained	Manual register entry	PICU		Only hibernate regulator active.

Table 6-3. Power Modes Wakeup Time and Power Consumption

Sleep Modes	Wakeup Time	Current (typ)	Code Execution	Digital Resources	Analog Resources	Clock Sources Available	Wakeup Sources	Reset Sources
Active	–	1.2 mA[13]	Yes	All	All	All	–	All
Alternate Active	–	–	User defined	All	All	All	–	All
Sleep	<15 µs	1 µA	No	I^2C	Comparator	ILO/kHzECO	Comparator, PICU, I^2C, RTC, CTW, LVD	XRES, LVD, WDR
Hibernate	<100 µs	200 nA	No	None	None	None	PICU	XRES

Note
13. Bus clock off. Execute from CPU instruction buffer at 6 MHz. See Table 11-2 on page 60.

Figure 6-5. Power Mode Transitions



6.2.1.1 Active Mode

Active mode is the primary operating mode of the device. When in active mode, the active configuration template bits control which available resources are enabled or disabled. When a resource is disabled, the digital clocks are gated, analog bias currents are disabled, and leakage currents are reduced as appropriate. User firmware can dynamically control subsystem power by setting and clearing bits in the active configuration template. The CPU can disable itself, in which case the CPU is automatically reenabled at the next wakeup event.

When a wakeup event occurs, the global mode is always returned to active, and the CPU is automatically enabled, regardless of its template settings. Active mode is the default global power mode upon boot.

6.2.1.2 Alternate Active Mode

Alternate Active mode is very similar to Active mode. In alternate active mode, fewer subsystems are enabled, to reduce power consumption. One possible configuration is to turn off the CPU and flash, and run peripherals at full speed.

6.2.1.3 Sleep Mode

Sleep mode reduces power consumption when a resume time of 15 µs is acceptable. The wake time is used to ensure that the regulator outputs are stable enough to directly enter active mode.

6.2.1.4 Hibernate Mode

In hibernate mode nearly all of the internal functions are disabled. Internal voltages are reduced to the minimal level to keep vital systems alive. Configuration state is preserved in hibernate mode and SRAM memory is retained. GPIOs configured as digital outputs maintain their previous values and external GPIO pin interrupt settings are preserved. The device can only return from hibernate mode in response to an external I/O interrupt. The resume time from hibernate mode is less than 100 µs.

6.2.1.5 Wakeup Events

Wakeup events are configurable and can come from an interrupt or device reset. A wakeup event restores the system to active mode. Firmware enabled interrupt sources include internally generated interrupts, power supervisor, central timewheel, and I/O interrupts. Internal interrupt sources can come from a variety of peripherals, such as analog comparators and UDBs. The central timewheel provides periodic interrupts to allow the system to wake up, poll peripherals, or perform real-time functions. Reset event sources include the external reset I/O pin (XRES), WDT, and precision reset (PRES).

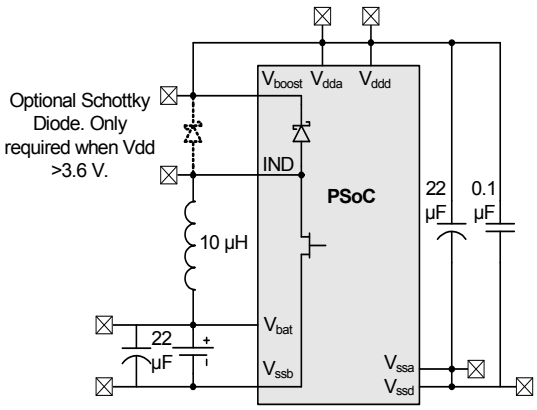
6.2.2 Boost Converter

Applications that use a supply voltage of less than 1.71 V, such as solar or single cell battery supplies, may use the on-chip boost converter. The boost converter may also be used in any system that requires a higher operating voltage than the supply provides. For instance, this includes driving 5.0 V LCD glass in a 3.3 V system. The boost converter accepts an input voltage as low as 0.5 V. With one low cost inductor it produces a selectable output voltage sourcing enough current to operate the PSoC and other on-board components.

The boost converter accepts an input voltage from 0.5 V to 5.5 V (V_{BAT}), and can start up with Vbat as low as 0.5 V. The converter provides a user configurable output voltage of 1.8 to 5.0 V (Vboost). Vbat is typically less than Vboost; if Vbat is greater than or equal to Vboost, then Vboost will be the same as Vbat. The block can deliver up to 50 mA (I_{BOOST}) depending on configuration.

Four pins are associated with the boost converter: Vbat, Vssb, Vboost, and Ind. The boosted output voltage is sensed at the Vboost pin and must be connected directly to the chip's supply inputs. An inductor is connected between the Vbat and Ind pins. You can optimize the inductor value to increase the boost converter efficiency based on input voltage, output voltage, current and switching frequency. The External Schottky diode shown in Figure 6-6 is required only in cases when Vboost > 3.6 V.

Figure 6-6. Application for Boost Converter



The switching frequency can be set to 100 kHz, 400 kHz, 2 MHz, or 32 kHz to optimize efficiency and component cost. The 100 kHz, 400 kHz, and 2 MHz switching frequencies are generated using oscillators internal to the boost converter block. When the 32-kHz switching frequency is selected, the clock is derived from a 32 kHz external crystal oscillator. The 32-kHz external clock is primarily intended for boost standby mode.

At 2 MHz the Vboost output is limited to 2 × Vbat, and at 400 kHz Vboost is limited to 4 × Vbat.

The boost converter can be operated in two different modes: active and standby. Active mode is the normal mode of operation where the boost regulator actively generates a regulated output

Figure 6-8. GPIO Block Diagram

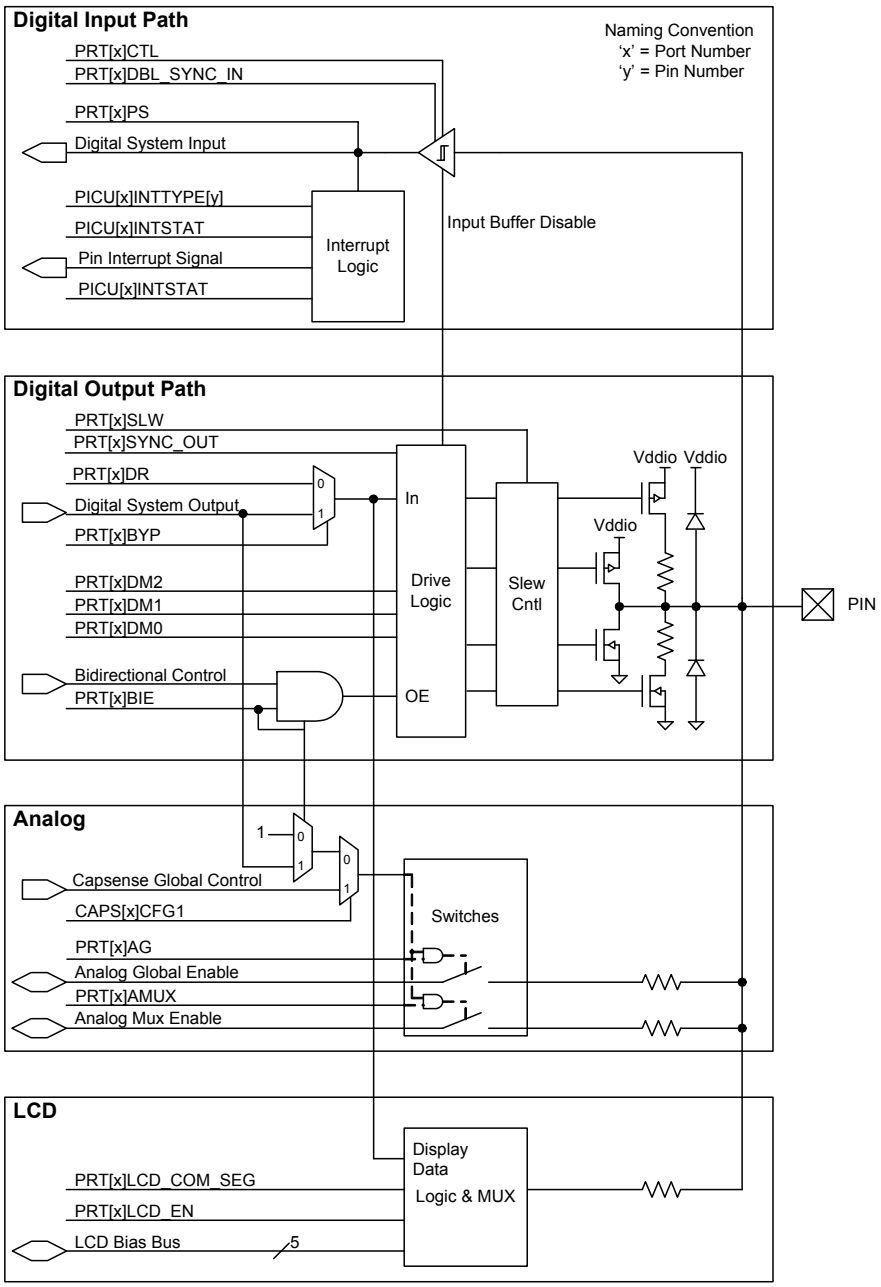
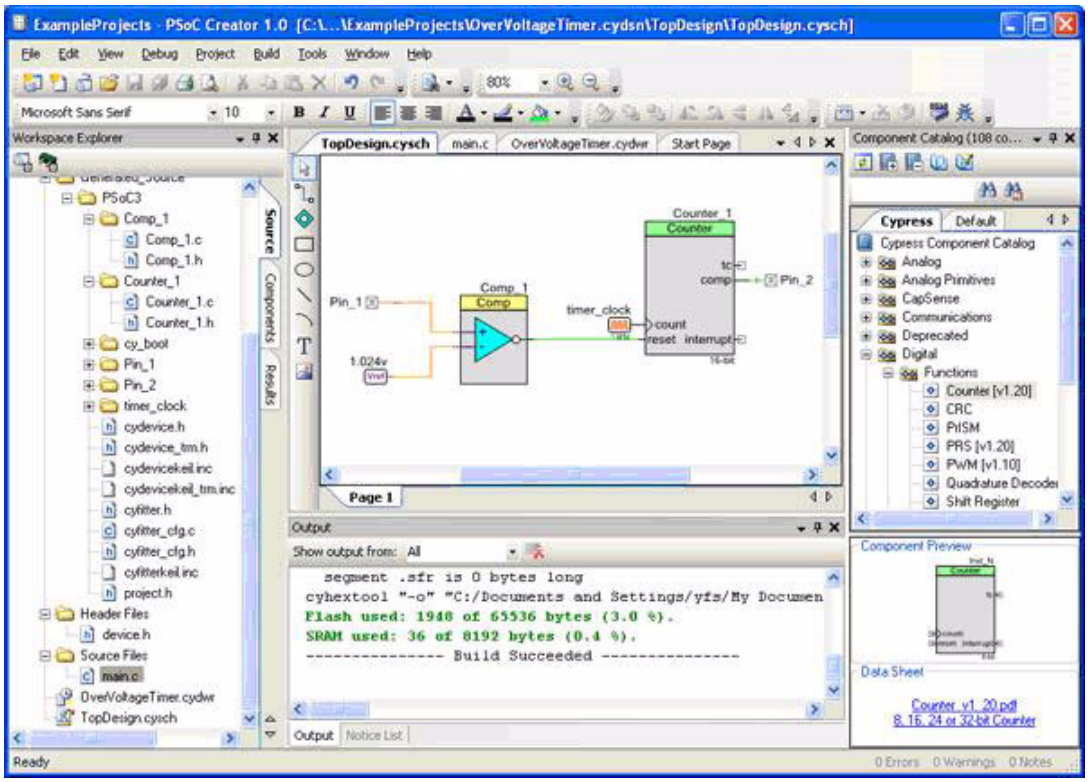
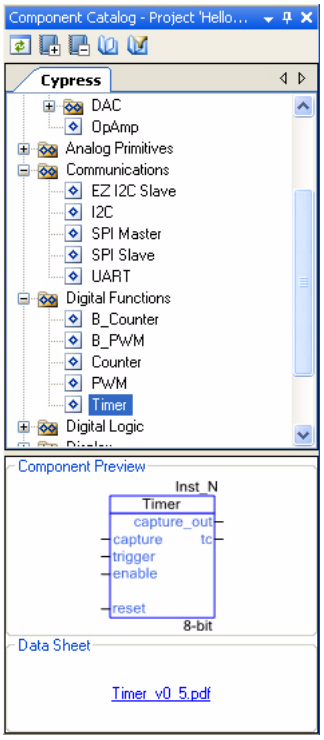


Figure 7-2. PSoC Creator Framework



7.1.4.2 Component Catalog

Figure 7-3. Component Catalog



The component catalog is a repository of reusable design elements that select device functionality and customize your PSoC device. It is populated with an impressive selection of content; from simple primitives such as logic gates and device registers, through the digital timers, counters and PWMs, plus analog components such as ADC, DACs, and filters, and communication protocols, such as I^2C, USB, and CAN. See Example Peripherals on page 35 for more details about available peripherals. All content is fully characterized and carefully documented in datasheets with code examples, AC/DC specifications, and user code ready APIs.

7.1.4.3 Design Reuse

The symbol editor gives you the ability to develop reusable components that can significantly reduce future design time. Just draw a symbol and associate that symbol with your proven design. PSoC Creator allows for the placement of the new symbol anywhere in the component catalog along with the content provided by Cypress. You can then reuse your content as many times as you want, and in any number of projects, without ever having to revisit the details of the implementation.

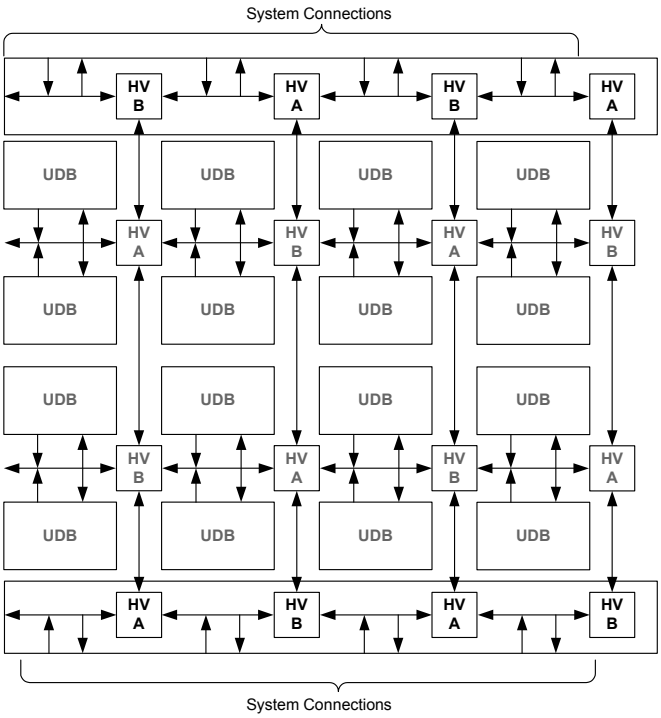
7.2.3.2 Clock Generation

Each subcomponent block of a UDB including the two PLDs, the datapath, and Status and Control, has a clock selection and control block. This promotes a fine granularity with respect to allocating clocking resources to UDB component blocks and allows unused UDB resources to be used by other functions for maximum system efficiency.

7.3 UDB Array Description

Figure 7-11 shows an example of a 16 UDB array. In addition to the array core, there are a DSI routing interfaces at the top and bottom of the array. Other interfaces that are not explicitly shown include the system interfaces for bus and clock distribution. The UDB array includes multiple horizontal and vertical routing channels each comprised of 96 wires. The wire connections to UDBs, at horizontal/vertical intersection and at the DSI interface are highly permutable providing efficient automatic routing in PSoC Creator. Additionally the routing allows wire by wire segmentation along the vertical and horizontal routing to further increase routing flexibility and capability.

Figure 7-11. Digital System Interface Structure

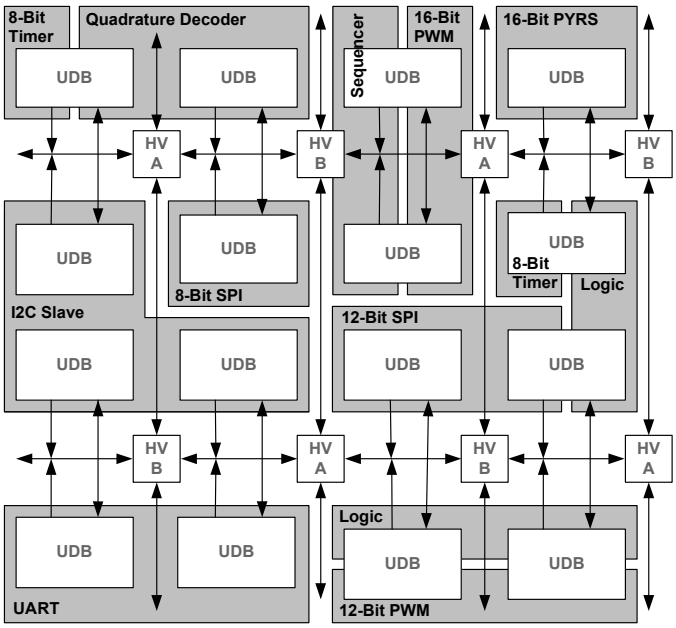


7.3.1 UDB Array Programmable Resources

Figure 7-12 shows an example of how functions are mapped into a bank of 16 UDBs. The primary programmable resources of the UDB are two PLDs, one datapath and one status/control register. These resources are allocated independently, because they have independently selectable clocks, and therefore unused blocks are allocated to other unrelated functions.

An example of this is the 8-bit timer in the upper left corner of the array. This function only requires one datapath in the UDB, and therefore the PLD resources may be allocated to another function. A function such as a Quadrature Decoder may require more PLD logic than one UDB can supply and in this case can utilize the unused PLD blocks in the 8-bit Timer UDB. Programmable resources in the UDB array are generally homogeneous so functions can be mapped to arbitrary boundaries in the array.

Figure 7-12. Function Mapping Example in a Bank of UDBs



7.4 DSI Routing Interface Description

The DSI routing interface is a continuation of the horizontal and vertical routing channels at the top and bottom of the UDB array core. It provides general purpose programmable routing between device peripherals, including UDBs, I/Os, analog peripherals, interrupts, DMA and fixed function peripherals.

Figure 7-13 illustrates the concept of the digital system interconnect, which connects the UDB array routing matrix with other device peripherals. Any digital core or fixed function peripheral that needs programmable routing is connected to this interface.

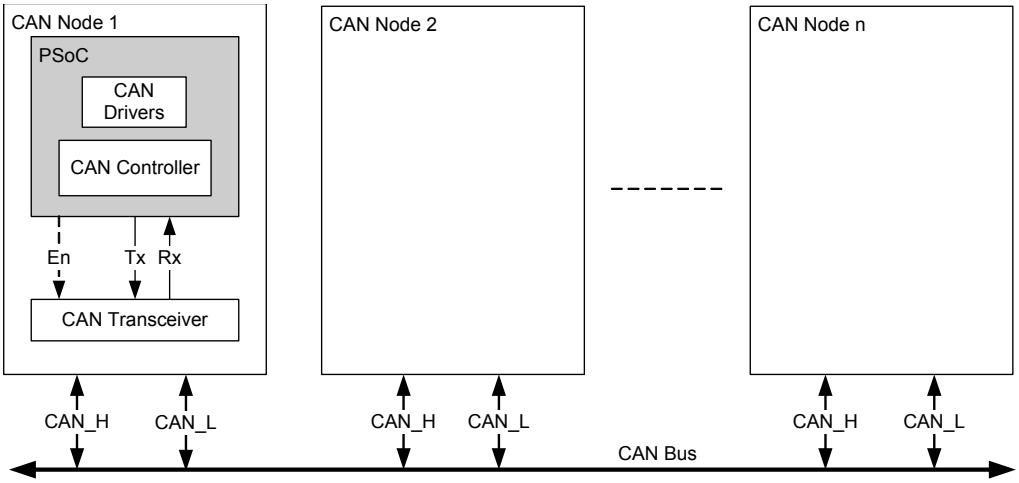
Signals in this category include:

- Interrupt requests from all digital peripherals in the system.
- DMA requests from all digital peripherals in the system.
- Digital peripheral data signals that need flexible routing to I/Os.
- Digital peripheral data signals that need connections to UDBs.
- Connections to the interrupt and DMA controllers.
- Connection to I/O pins.
- Connection to analog system digital signals.

7.5 CAN

The CAN peripheral is a fully functional controller area network (CAN) supporting communication baud rates up to 1 Mbps. The CAN controller implements the CAN2.0A and CAN2.0B specifications as defined in the Bosch specification and conforms to the ISO-11898-1 standard. The CAN protocol was originally designed for automotive applications with a focus on a high level of fault detection. This ensures high communication reliability at a low cost. Because of its success in automotive applications, CAN is used as a standard communication protocol for motion oriented machine control networks (CANOpen) and factory automation applications (DeviceNet). The CAN controller features allow the efficient implementation of higher level protocols without affecting the performance of the microcontroller CPU. Full configuration support is provided in PSoC Creator.

Figure 7-18. CAN Bus System Implementation



7.5.1 CAN Features

- CAN2.0A/B protocol implementation – ISO 11898 compliant
  - Standard and extended frames with up to 8 bytes of data per frame
  - Message filter capabilities
  - Remote Transmission Request (RTR) support
  - Programmable bit rate up to 1 Mbps
- Listen Only mode
- SW readable error counter and indicator
- Sleep mode: Wake the device from sleep with activity on the Rx pin
- Supports two or three wire interface to external transceiver (Tx, Rx, and Enable). The three-wire interface is compatible with the Philips PHY; the PHY is not included on-chip. The three wires can be routed to any I/O
- Enhanced interrupt controller
  - CAN receive and transmit buffers status
  - CAN controller error status including BusOff
- Receive path
  - 16 receive buffers each with its own message filter
  - Enhanced hardware message filter implementation that covers the ID, IDE, and RTR
  - DeviceNet addressing support
  - Multiple receive buffers linkable to build a larger receive message array
  - Automatic transmission request (RTR) response handler
  - Lost received message notification
- Transmit path
  - Eight transmit buffers
  - Programmable transmit priority
  - Round robin
  - Fixed priority
  - Message transmissions abort capability

7.5.2 Software Tools Support

CAN Controller configuration integrated into PSoC Creator:

- CAN Configuration walkthrough with bit timing analyzer
- Receive filter setup

11.2 Device Level Specifications

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

11.2.1 Device Level Specifications

Table 11-2. DC Specifications

Parameter	Description	Conditions		Min	Typ	Max	Units
V_{DDA}	Analog supply voltage and input to analog core regulator	Analog core regulator enabled		1.8	–	5.5	V
V_{DDA}	Analog supply voltage, analog regulator bypassed	Analog core regulator disabled		1.71	1.8	1.89	V
V_{DDD}	Digital supply voltage relative to V_{SSD}	Digital core regulator enabled		1.8	–	V_{DDA}[19]	V
V_{DDD}	Digital supply voltage, digital regulator bypassed	Digital core regulator disabled		1.71	1.8	1.89	V
V_{DDIO}[20]	I/O supply voltage relative to V_{SSIO}			1.71	–	V_{DDA}[19]	V
V_{CCA}	Direct analog core voltage input (Analog regulator bypass)	Analog core regulator disabled		1.71	1.8	1.89	V
V_{CCD}	Direct digital core voltage input (Digital regulator bypass)	Digital core regulator disabled		1.71	1.8	1.89	V
V_{BAT}	Voltage supplied to boost converter			0.5	–	5.5	V
I_{DD}[21]	**Active Mode, V_{DD} = 1.71 V–5.5 V**						
	Bus clock off. Execute from CPU instruction buffer. See "Flash Program Memory" on page 18.	CPU at 3 MHz	T = –40 °C	–	–	–	mA
			T = 25 °C	–	0.8	–	mA
			T = 85 °C	–	–	–	mA
		CPU at 6 MHz	T = –40 °C	–	–	–	mA
			T = 25 °C	–	1.2	–	mA
			T = 85 °C	–	–	–	mA
		CPU at 12 MHz	T = –40 °C	–	–	–	mA
			T = 25 °C	–	2.0	–	mA
			T = 85 °C	–	–	–	mA
		CPU at 24 MHz	T = –40 °C	–	–	–	mA
			T = 25 °C	–	3.5	–	mA
			T = 85 °C	–	–	–	mA
		CPU at 48 MHz	T = –40 °C	–	–	–	mA
			T = 25 °C	–	6.6	–	mA
			T = 85 °C	–	–	–	mA
		CPU at 62.6 MHz	T = –40 °C	–	–	–	mA
			T = 25 °C	–	9.0	–	mA
			T = 85 °C	–	–	–	mA
	V_{DD} = 3.3 V, T = 25 °C, IMO and bus clock enabled, ILO = 1 kHz, CPU executing from flash and accessing SRAM, all other blocks off, all I/Os tied low.	CPU at 3 MHz		–	1.2	–	mA
		CPU at 6 MHz		–	1.8	–	mA
		CPU at 12 MHz		–	3.2	–	mA
		CPU at 24 MHz		–	5.8	–	mA
		CPU at 48 MHz		–	12.1	–	mA
		CPU at 62.6 MHz		–	15.6	–	mA

Notes
19. The power supplies can be brought up in any sequence however once stable V_{DDA} must be greater than or equal to all other supplies.
20. The V_{DDIO} supply voltage must be greater than the maximum analog voltage on the associated GPIO pins. Maximum analog voltage on GPIO pin ≤ V_{DDIO} ≤ V_{DDA}.
21. The current consumption of additional peripherals that are implemented only in programmed logic blocks can be found in their respective datasheets, available in PSoC Creator, the integrated design environment. To estimate total current, find CPU current at frequency of interest and add peripheral currents for your particular system from the device datasheet and component datasheets.

Table 11-2. DC Specifications *(continued)*

Parameter	Description	Conditions		Min	Typ	Max	Units
	Sleep Mode[22]						
	CPU = OFF RTC = ON (= ECO32K ON, in low-power mode) Sleep timer = ON (= ILO ON at 1 kHz)[23] WDT = OFF I^2C Wake = OFF Comparator = OFF POR = ON Boost = OFF SIO pins in single ended input, unregulated output mode	$V_{DD} = V_{DDIO}$ = 4.5–5.5 V	T = –40 °C	–	–	–	µA
			T = 25 °C	–	–	–	µA
			T = 85 °C	–	–	–	µA
		$V_{DD} = V_{DDIO}$ = 2.7–3.6 V	T = –40 °C	–	–	–	µA
			T = 25 °C	–	1	–	µA
			T = 85 °C	–	–	–	µA
		$V_{DD} = V_{DDIO}$ = 1.71–1.95 V	T = –40 °C	–	–	–	µA
			T = 25 °C	–	–	–	µA
			T = 85 °C	–	–	–	µA
	Comparator = ON CPU = OFF RTC = OFF Sleep timer = OFF WDT = OFF I2C Wake = OFF POR = ON Boost = OFF SIO pins in single ended input, unregulated output mode	$V_{DD} = V_{DDIO}$ = 2.7–3.6V	T = 25 °C	–	–	–	µA
	I2C Wake = ON CPU = OFF RTC = OFF Sleep timer = OFF WDT = OFF Comparator = OFF POR = ON Boost = OFF SIO pins in single ended input, unregulated output mode	$V_{DD} = V_{DDIO}$ = 2.7–3.6V	T = 25 °C	–	–	–	µA
	Hibernate Mode[22]						
	Hibernate mode current All regulators and oscillators off. SRAM retention GPIO interrupts are active Boost = OFF SIO pins in single ended input, unregulated output mode	$V_{DD} = V_{DDIO}$ = 4.5–5.5 V	T = –40 °C	–	–	–	nA
			T = 25 °C	–	–	–	nA
			T = 85 °C	–	–	–	nA
		$V_{DD} = V_{DDIO}$ = 2.7–3.6 V	T = –40 °C	–	–	–	nA
			T = 25 °C	–	200	–	nA
			T = 85 °C	–	–	–	nA
		$V_{DD} = V_{DDIO}$ = 1.71–1.95 V	T = –40 °C	–	–	–	nA
			T = 25 °C	–	–	–	nA
			T = 85 °C	–	–	–	nA

Notes
22. If V_{CCD} and V_{CCA} are externally regulated, the voltage difference between V_{CCD} and V_{CCA} must be less than 50 mV.
23. Sleep timer generates periodic interrupts to wake up the CPU. This specification applies only to those times that the CPU is off.

11.4.2 SIO

Table 11-11. SIO DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Vinmax	Maximum input voltage	All allowed values of Vddio and Vddd, see *Section 11.2.1*	–	–	5.5	V
Vinref	Input voltage reference (Differential input mode)		0.5	–	$0.52 \times V_{DDIO}$	V
Voutref	Output voltage reference (Regulated output mode)					
		$V_{DDIO} > 3.7$	1	–	$V_{DDIO} - 1$	V
		$V_{DDIO} < 3.7$	1	–	$V_{DDIO} - 0.5$	V
V_{IH}	Input voltage high threshold					
	GPIO mode	CMOS input	$0.7 \times V_{DDIO}$	–	–	V
	Differential input mode[30]	Hysteresis disabled	SIO_ref + 0.2	–	–	V
V_{IL}	Input voltage low threshold					
	GPIO mode	CMOS input	–	–	$0.3 \times V_{DDIO}$	V
	Differential input mode[30]	Hysteresis disabled	–	–	SIO_ref – 0.2	V
V_{OH}	Output voltage high					
	Unregulated mode	I_{OH} = 4 mA, V_{DDIO} = 3.3 V	$V_{DDIO} - 0.4$	–	–	V
	Regulated mode[30]	I_{OH} = 1 mA	SIO_ref – 0.65	–	SIO_ref + 0.2	V
	Regulated mode[30]	I_{OH} = 0.1 mA	SIO_ref – 0.3	–	SIO_ref + 0.2	V
V_{OL}	Output voltage low					
		V_{DDIO} = 3.30 V, I_{OL} = 25 mA	–	–	0.8	V
		V_{DDIO} = 1.80 V, I_{OL} = 4 mA	–	–	0.4	V
Rpullup	Pull-up resistor		3.5	5.6	8.5	kΩ
Rpulldown	Pull-down resistor		3.5	5.6	8.5	kΩ
I_{IL}	Input leakage current (Absolute value)[31]					
	$V_{IH} \leq$ Vddsio	25 °C, Vddsio = 3.0 V, V_{IH} = 3.0 V	–	–	14	nA
	V_{IH} > Vddsio	25 °C, Vddsio = 0 V, V_{IH} = 3.0 V	–	–	10	µA
C_{IN}	Input Capacitance[31]		–	–	7	pF
V_H	Input voltage hysteresis (Schmitt-Trigger)[31]	Single ended mode (GPIO mode)	–	40	–	mV
		Differential mode	–	35	–	mV
Idiode	Current through protection diode to V_{SSIO}		–	–	100	µA

Table 11-12. SIO AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
TriseF	Rise time in fast strong mode (90/10%)[31]	Cload = 25 pF, V_{DDIO} = 3.3 V	–	–	12	ns
TfallF	Fall time in fast strong mode (90/10%)[31]	Cload = 25 pF, V_{DDIO} = 3.3 V	–	–	12	ns
TriseS	Rise time in slow strong mode (90/10%)[31]	Cload = 25 pF, V_{DDIO} = 3.0 V	–	–	75	ns
TfallS	Fall time in slow strong mode (90/10%)[31]	Cload = 25 pF, V_{DDIO} = 3.0 V	–	–	60	ns

Notes
30. See Figure 6-9 on page 30 and Figure 6-12 on page 33 for more information on SIO reference.
31. Based on device characterization (Not production tested).

Table 11-19. Opamp AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
GBW	Gain-bandwidth product	Power mode = minimum, 200 pF load	1	–	–	MHz
		Power mode = low, 200 pF load	2	–	–	MHz
		Power mode = medium, 200 pF load	1	–	–	MHz
		Power mode = high, 200 pF load	3	–	–	MHz
SR	Slew rate, 20% - 80%	Power mode = low, 200 pF load	1.1	–	–	V/µs
		Power mode = medium, 200 pF load	0.9	–	–	V/µs
		Power mode = high, 200 pF load	3	–	–	V/µs
e_n	Input noise density	Power mode = high, Vdda = 5 V, at 100 kHz	–	45	–	nV/sqrtHz

Figure 11-10. Open Loop Gain and Phase vs Frequency and Temperature, Power Mode = High, Cl = 15 Pf, Vdda = 5V

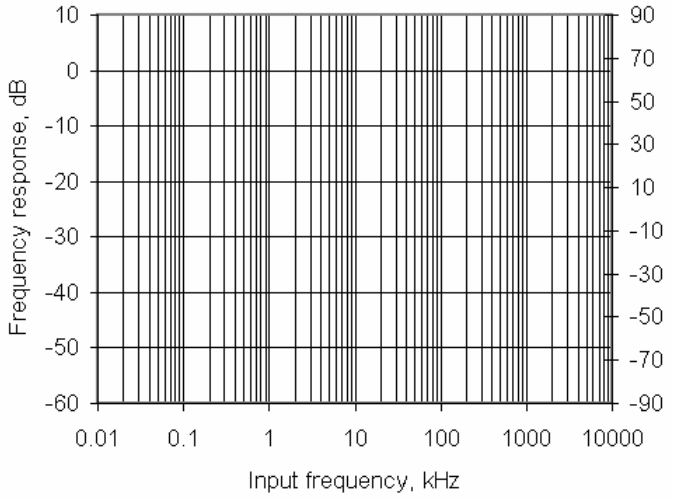


Figure 11-11. Opamp Closed Loop Frequency Response, Gain = 1, Vdda = 5V

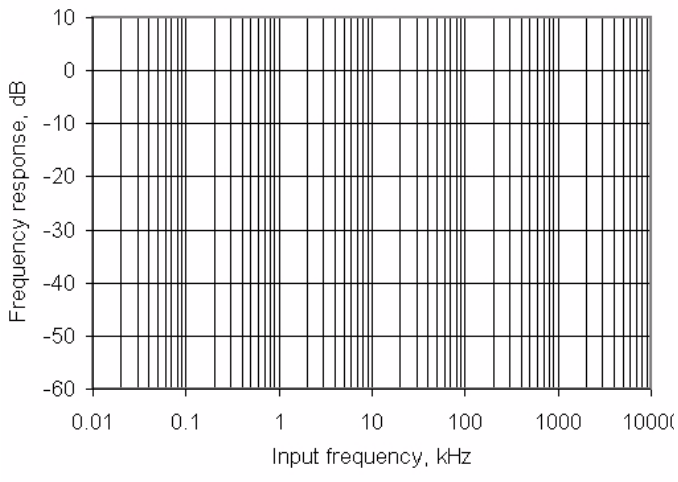


Table 11-20. 20-bit Delta-sigma ADC DC Specifications *(continued)*

Parameter	Description	Conditions	Min	Typ	Max	Units
Vextref	ADC external reference input voltage, see also internal reference in Voltage Reference on page 80	Pins P0[3], P3[2]	0.9	–	1.3	V
Current Consumption						
I_{DD_20}	Current consumption, 20 bit[35]	187 sps, unbuffered	–	–	1.25	mA
I_{DD_16}	Current consumption, 16 bit[35]	48 ksps, unbuffered	–	–	1.2	mA
I_{DD_12}	Current consumption, 12 bit[35]	192 ksps, unbuffered	–	–	1.4	mA
I_{BUFF}	Buffer current consumption[35]		–	–	2.5	mA

Table 11-21. Delta-sigma ADC AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Startup time		–	–	4	Samples
THD	Total harmonic distortion[35]	Buffer gain = 1, 16 bit, Range = ±1.024 V	–	–	0.0032	%
20-Bit Resolution Mode						
SR20	Sample rate[35]	Range = ±1.024 V, unbuffered	7.8	–	187	sps
BW20	Input bandwidth at max sample rate[35]	Range = ±1.024 V, unbuffered	–	40	–	Hz
16-Bit Resolution Mode						
SR16	Sample rate[35]	Range = ±1.024 V, unbuffered	2	–	48	ksps
BW16	Input bandwidth at max sample rate[35]	Range = ±1.024 V, unbuffered	–	11	–	kHz
SINAD16int	Signal to noise ratio, 16-bit, internal reference[35]	Range = ±1.024V, unbuffered	81	–	–	dB
SINAD16ext	Signal to noise ratio, 16-bit, external reference[35]	Range = ±1.024 V, unbuffered	84	–	–	dB
12-Bit Resolution Mode						
SR12	Sample rate, continuous, high power[35]	Range = ±1.024 V, unbuffered	4	–	192	ksps
BW12	Input bandwidth at max sample rate[35]	Range = ±1.024 V, unbuffered	–	44	–	kHz
SINAD12int	Signal to noise ratio, 12-bit, internal reference[35]	Range = ±1.024 V, unbuffered	66	–	–	dB
8-Bit Resolution Mode						
SR8	Sample rate, continuous, high power[35]	Range = ±1.024 V, unbuffered	8	–	384	ksps
BW8	Input bandwidth at max sample rate[35]	Range = ±1.024 V, unbuffered	–	88	–	kHz
SINAD8int	Signal to noise ratio, 8-bit, internal reference[35]	Range = ±1.024 V, unbuffered	43	–	–	dB

Notes
35. Based on device characterization (Not production tested).

Figure 11-39. VDAC Full Scale Error vs Temperature, 1 V Mode

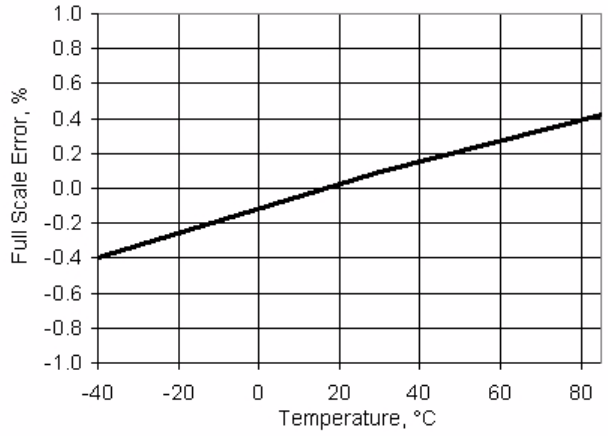


Figure 11-40. VDAC Full Scale Error vs Temperature, 4 V Mode

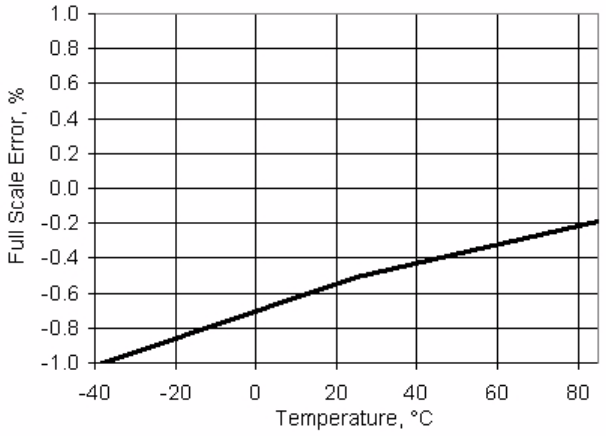


Figure 11-41. VDAC Operating Current vs Temperature, 1V Mode, Slow Mode

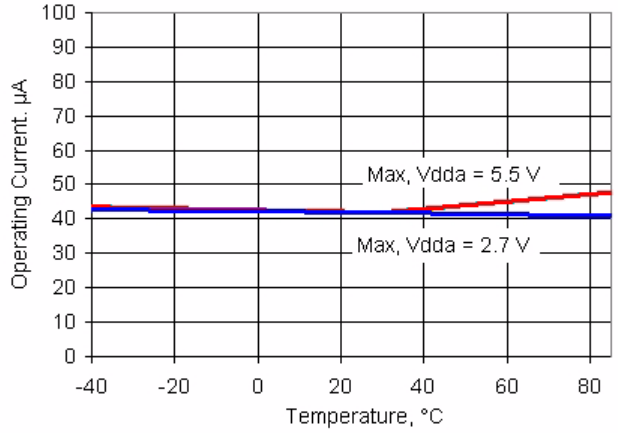


Figure 11-42. VDAC Operating Current vs Temperature, 1 V Mode, Fast Mode

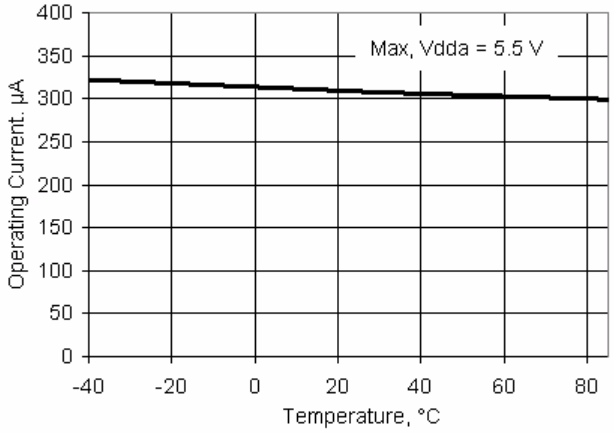


Table 11-32. VDAC AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
F_{DAC}	Update rate	1 V scale	–	–	1000	ksps
		4 V scale	–	–	250	ksps
TsettleP	Settling time to 0.1%, step 25% to 75%	1 V scale, Cload = 15 pF	–	0.45	1	µs
		4 V scale, Cload = 15 pF	–	0.8	3.2	µs
TsettleN	Settling time to 0.1%, step 75% to 25%	1 V scale, Cload = 15 pF	–	0.45	1	µs
		4 V scale, Cload = 15 pF	–	0.7	3	µs

11.5.12 LCD Direct Drive

Table 11-40. LCD Direct Drive DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
I_{CC}	LCD system operating current	Device sleep mode with wakeup at 400-Hz rate to refresh LCDs, bus clock = 3 Mhz, Vddio = Vdda = 3 V, 4 commons, 16 segments, 1/4 duty cycle, 50 Hz frame rate, no glass connected	–	38	–	µA
I_{CC_SEG}	Current per segment driver	Strong drive mode	–	260	–	µA
V_{BIAS}	LCD bias range (V_{BIAS} refers to the main output voltage(V0) of LCD DAC)	$V_{DDA} \geq 3$ V and $V_{DDA} \geq V_{BIAS}$	2	–	5	V
	LCD bias step size	$V_{DDA} \geq 3$ V and $V_{DDA} \geq V_{BIAS}$	–	$9.1 \times V_{DDA}$	–	mV
	LCD capacitance per segment/common driver	Drivers may be combined	–	500	5000	pF
	Long term segment offset		–	–	20	mV
I_{OUT}	Output drive current per segment driver)	Vddio = 5.5V, strong drive mode	355	–	710	µA

Table 11-41. LCD Direct Drive AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
f_{LCD}	LCD frame rate		10	50	150	Hz

Figure 11-51. Synchronous Write Cycle Timing

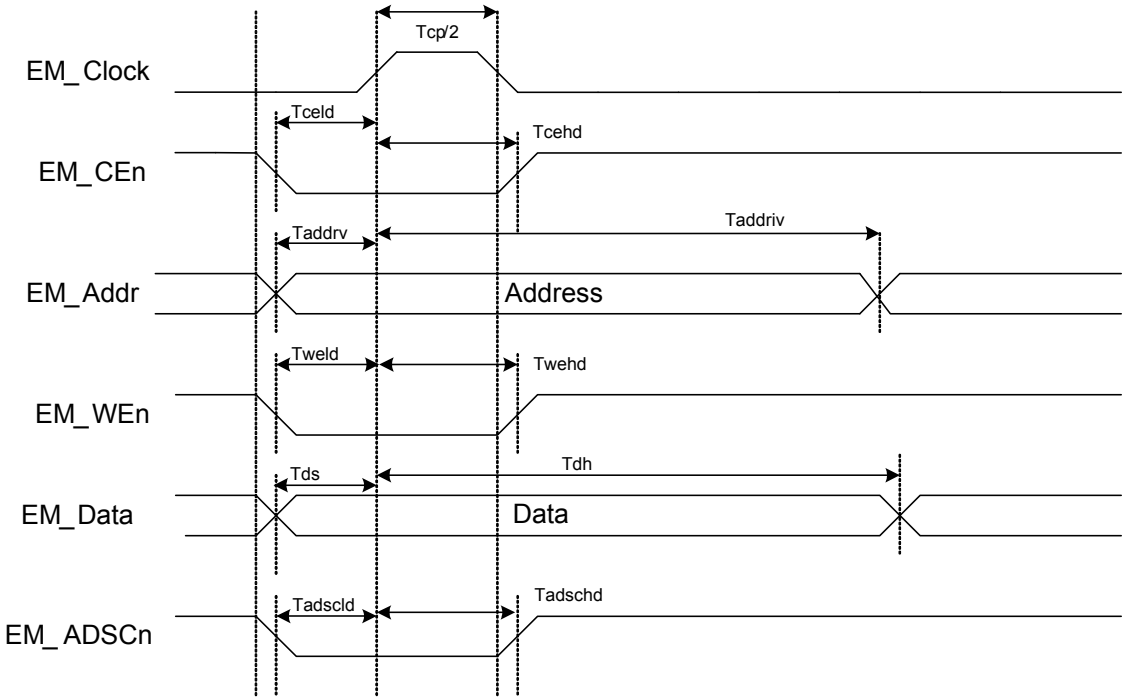


Table 11-66. Synchronous Write Cycle Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
T	EMIF clock Period[45]	Vdda ≥ 3.3 V	30.3	–	–	nS
Tcp/2	EM_Clock pulse high		T/2	–	–	nS
Tceld	EM_CEn low to EM_Clock high		5	–	–	nS
Tcehd	EM_Clock high to EM_CEn high		T/2 – 5	–	–	nS
Taddrv	EM_Addr valid to EM_Clock high		5	–	–	nS
Taddriv	EM_Clock high to EM_Addr invalid		T/2 – 5	–	–	nS
Tweld	EM_WEn low to EM_Clock high		5	–	–	nS
Twehd	EM_Clock high to EM_WEn high		T/2 – 5	–	–	nS
Tds	Data valid before EM_Clock high		5	–	–	nS
Tdh	Data invalid after EM_Clock high		T	–	–	nS
Tadscld	EM_ADSCn low to EM_Clock high		5	–	–	nS
Tadschd	EM_Clock high to EM_ADSCn high		T/2 – 5	–	–	nS

Note
45. Limited by GPIO output frequency, see Table 11-10 on page 65.

11.8 PSoC System Resources

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

11.8.1 POR with Brown Out

For brown out detect in regulated mode, V_{DDD} and V_{DDA} must be ≥ 2.0 V. Brown out detect is not available in externally regulated mode.

Table 11-67. Precise Power On Reset (PRES) with Brown Out DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Precise POR (PPOR)					
PRESR	Rising trip voltage	Factory trim	1.64	–	1.68	V
PRESF	Falling trip voltage		1.62	–	1.66	V

Table 11-68. Power On Reset (POR) with Brown Out AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
PRES_TR	Response time		–	–	0.5	µs

11.8.2 Voltage Monitors

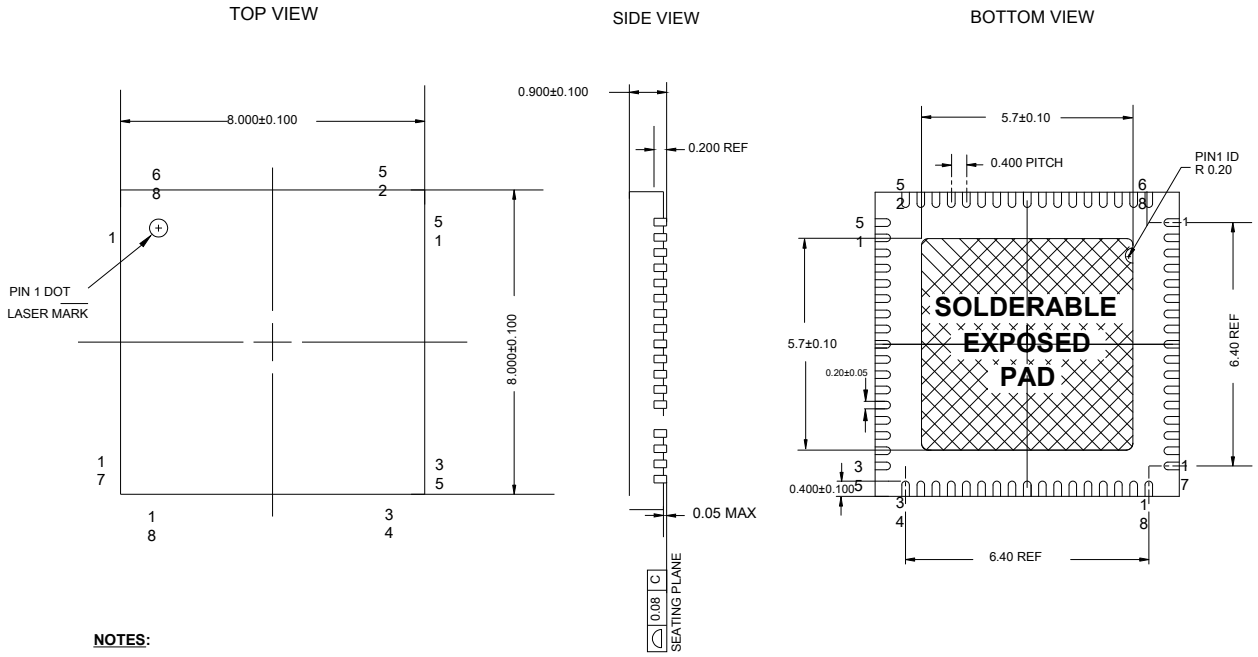
Table 11-69. Voltage Monitors DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
LVI	Trip voltage					
	LVI_A/D_SEL[3:0] = 0000b		1.68	1.73	1.77	V
	LVI_A/D_SEL[3:0] = 0001b		1.89	1.95	2.01	V
	LVI_A/D_SEL[3:0] = 0010b		2.14	2.20	2.27	V
	LVI_A/D_SEL[3:0] = 0011b		2.38	2.45	2.53	V
	LVI_A/D_SEL[3:0] = 0100b		2.62	2.71	2.79	V
	LVI_A/D_SEL[3:0] = 0101b		2.87	2.95	3.04	V
	LVI_A/D_SEL[3:0] = 0110b		3.11	3.21	3.31	V
	LVI_A/D_SEL[3:0] = 0111b		3.35	3.46	3.56	V
	LVI_A/D_SEL[3:0] = 1000b		3.59	3.70	3.81	V
	LVI_A/D_SEL[3:0] = 1001b		3.84	3.95	4.07	V
	LVI_A/D_SEL[3:0] = 1010b		4.08	4.20	4.33	V
	LVI_A/D_SEL[3:0] = 1011b		4.32	4.45	4.59	V
	LVI_A/D_SEL[3:0] = 1100b		4.56	4.70	4.84	V
	LVI_A/D_SEL[3:0] = 1101b		4.83	4.98	5.13	V
	LVI_A/D_SEL[3:0] = 1110b		5.05	5.21	5.37	V
	LVI_A/D_SEL[3:0] = 1111b		5.30	5.47	5.63	V
HVI	Trip voltage		5.57	5.75	5.92	V

Table 11-70. Voltage Monitors AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Response time		–	–	1	µs

Figure 13-3. 68-pin QFN 8×8 with 0.4 mm Pitch Package Outline (Sawn Version)

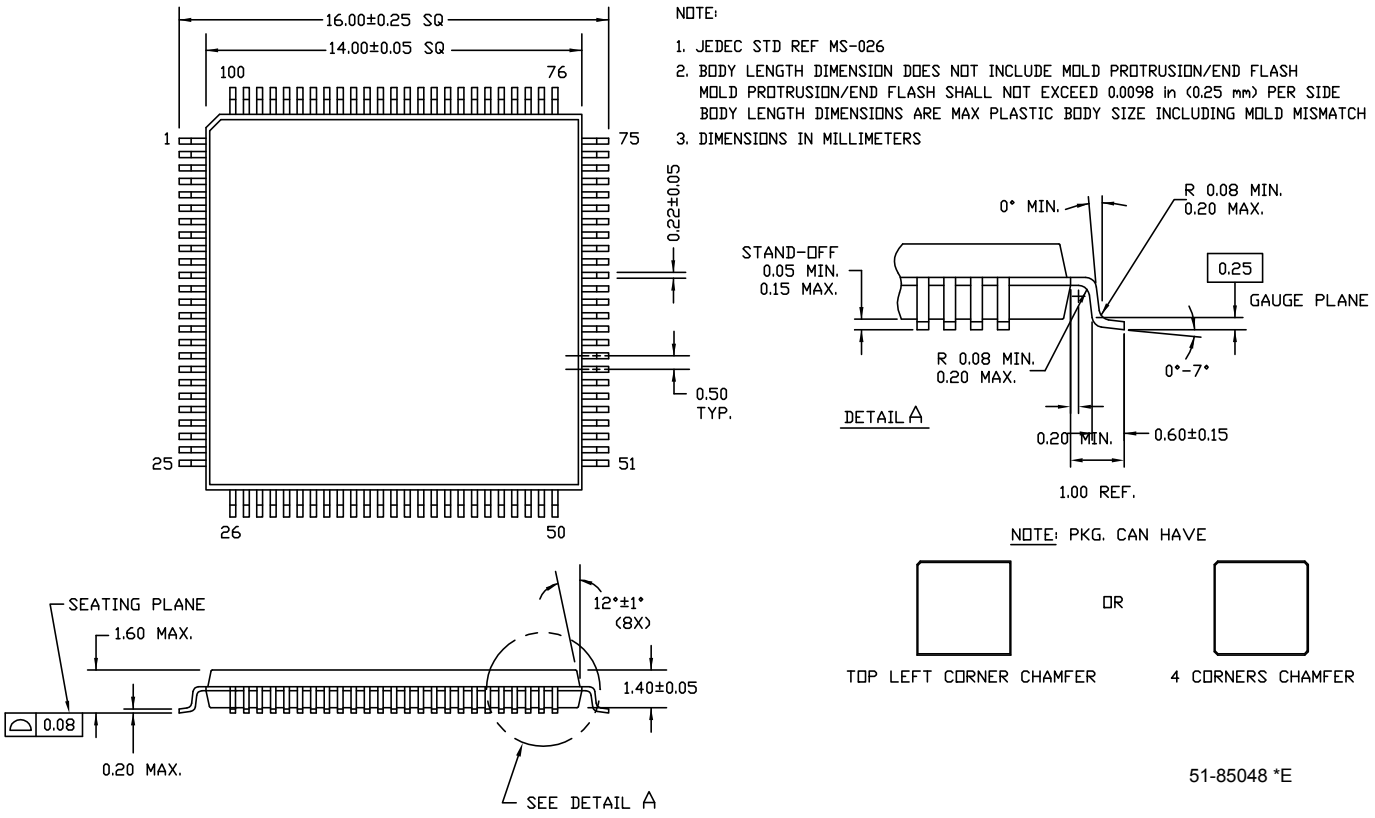


NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO-220
3. PACKAGE WEIGHT: 0.17g
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-09618 *C

Figure 13-4. 100-pin TQFP (14 × 14 × 1.4 mm) Package Outline



51-85048 *E

Table 14-1. Acronyms Used in this Document *(continued)*

Acronym	Description
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration datasheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I^2C serial clock
SDA	I^2C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol
SWV	single-wire viewer
TD	transaction descriptor, see also DMA

Table 14-1. Acronyms Used in this Document *(continued)*

Acronym	Description
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

15. Reference Documents

PSoC® 3, PSoC® 5 Architecture TRM

PSoC® 3 Registers TRM

16. Document Conventions

16.1 Units of Measure

Table 16-1. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibels
fF	femtofarads
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohours
kHz	kilohertz
kΩ	kilohms
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	megaohms
Msps	megasamples per second

Table 16-1. Units of Measure *(continued)*

Symbol	Unit of Measure
µA	microamperes
µF	microfarads
µH	microhenrys
µs	microseconds
µV	microvolts
µW	microwatts
mA	milliamperes
ms	milliseconds
mV	millivolts
nA	nanoamperes
ns	nanoseconds
nV	nanovolts
Ω	ohms
pF	picofarads
ppm	parts per million
ps	picoseconds
s	seconds
sps	samples per second
sqrtHz	square root of hertz
V	volts

Description Title: PSoC® 3: CY8C38 Family Datasheet Programmable System-on-Chip (PSoC®) Document Number: 001-11729				
*K	2903576	04/01/2010	MKEA	Updated Vb pin in PCB Schematic. Updated Tstartup parameter in AC Specifications table. Added Load regulation and Line regulation parameters to Inductive Boost Regulator DC Specifications table. Updated I_{CC} parameter in LCD Direct Drive DC Specs table. In page 1, updated internal oscillator range under Precision programmable clocking to start from 3 MHz. Updated I_{OUT} parameter in LCD Direct Drive DC Specs table. Updated Table 6-2 and Table 6-3. Added bullets on CapSense in page 1; added CapSense column in Section 12. Removed some references to footnote [1]. Changed INC_Rn cycles from 3 to 2 (Table 4-1). Added footnote in PLL AC Specification table. Added PLL intermediate frequency row with footnote in PLL AC Specs table. Added UDBs subsection under 11.6 Digital Peripherals. Updated Figure 2-6 (PCB Layout). Updated Pin Descriptions section and modified Figures 6-6, 6-8, 6-9. Updated LVD in Tables 6-2 and 6-3; modified Low-power modes bullet in page 1. Added note to Figures 2-5 and 6-2; Updated Figure 6-2 to add capacitors for V_{DDA} and V_{DDD} pins. Updated boost converter section (6.2.2). Updated Tstartup values in Table 11-3. Removed IPOR rows from Table 11-68. Updated 6.3.1.1, Power Voltage Level Monitors. Updated section 5.2 and Table 11-2 to correct suggestion of execution from flash. Updated V_{REF} specs in Table 11-21. Updated IDAC uncompensated gain error in Table 11-25. Updated Delay from Interrupt signal input to ISR code execution from ISR code in Table11-72. Removed other line in table. Added sentence to last paragraph of section 6.1.1.3. Updated T_{RESP}, high and low-power modes, in Table 11-24. Updated f_TCK values in Table 11-73 and f_SWDCK values in Table 11-74. Updated SNR condition in Table 11-20. Corrected unit of measurement in Table 11-21. Updated sleep wakeup time in Table 6-3 and Tsleep in Table 11-3. Added 1.71 V <= V_{DDD} < 3.3 V, SWD over USBIO pins value to Table 11-74. Removed mention of hibernate reset (HRES) from page 1 features, Table 6-3, Section 6.2.1.4, Section 6.3, and Section 6.3.1.1. Changed PPOR/PRES to TBDs in Section 6.3.1.1, Section 6.4.1.6 (changed PPOR to reset), Table 11-3 (changed PPOR to PRES), Table 11-68 (changed title, values TBD), and Table 11-69 (changed PPOR_TR to PRES_TR). Added sentence saying that LVD circuits can generate a reset to Section 6.3.1.1. Changed I_{DD} values on page 1, page 5, and Table 11-2. Changed resume time value in Section 6.2.1.3. Changed ESD HBM value in Table 11-1. Changed SNR in 16-bit resolution mode value and sample rate row in Table 11-20. Removed V_{DDA} = 1.65 V rows and changed BWag value in Table 11-22. Changed V_{IOFF} values and changed CMRR value in Table 11-23. Changed INL max value in Table 11-27. Added max value to the Quiescent current specs in Tables 11-29 and 11-31. Changed occurrences of “Block” to “Row” and deleted the “ECC not included” footnote in Table 11-57. Changed max response time value in Tables 11-69 and 11-71. Changed the Startup time in Table 11-79. Added condition to intermediate frequency row in Table 11-85. Added row to Table 11-69. Added brown out note to Section 11.8.1.